

WHAT IS CLAIMED IS:

1. A packaging method for electronic parts comprising:
 - forming an opening in a first substrate;
 - 5 laminating a second substrate on the first substrate;
 - covering the opening with the second substrate;
 - inserting a first electronic part into the opening and bonding the first electronic part to the second
 - 10 substrate;
 - filling an interior of the opening with a resin to a fixed or larger thickness; and
 - hardening the resin;
 - wherein the first substrate and the first
 - 15 electronic part are thereby sustained by the resin, a second electronic part that should be connected to the first electronic part is bonded to a surface, on an exposed side, of the second substrate, and the first electronic part is connected to the second electronic part.
- 20 2. A packaging structure for electronic parts comprising:
 - a first substrate having an opening;
 - a second substrate laminated on the first
 - substrate and covering the opening;
 - 25 a first electronic part inserted into the opening and bonded to the second substrate;
 - a hard resin filling an interior of the opening

to a fixed or larger thickness;

a second electronic part bonded to a surface, on an exposed side, of the second substrate; and wiring for connecting the first electronic part to the second
5 electronic part.

3. A packaging structure for electronic parts according to claim 2, wherein the second substrate is a thin film.

4. A packaging structure for electronic parts
10 according to claim 2, wherein the first electronic part is a capacitor, and the second electronic part is an LSI.

5. A packaging structure for electronic parts according to claim 2, wherein the resin contains a filler agent.

15 6. A packaging structure for electronic parts according to claim 2, wherein a coefficient of thermal expansion of the resin is adjusted according to the first and second substrates, and the first and second electronic parts.

20 7. A packaging structure for electronic parts according to claim 2, wherein the first substrate includes a sustaining member provided within the opening and sustaining an exposed surface of the resin.

8. A packaging structure for electronic parts
25 according to claim 7, wherein a fin for cooling is bonded to the second electronic part.

9. A packaging structure for electronic parts

according to claim 2, wherein the second substrate has a stiffener for reinforcement.

10. A packaging structure for electronic parts according to claim 9, wherein the stiffener is provided
5 on the side of the first electronic part.

11. A packaging structure for electronic parts according to claim 9, wherein the stiffener is provided on an outer peripheral edge of the thin film substrate.

12. A packaging method for electronic parts
10 according to claim 1, wherein the second substrate is a thin film.

13. A packaging method for electronic parts according to claim 1, wherein the first electronic part is a capacitor, and the second electronic part is an LSI.

15 14. A packaging method for electronic parts according to claim 1, wherein the resin contains a filler agent.

15. A packaging method for electronic parts according to claim 1, wherein a coefficient of thermal
20 expansion of the resin is adjusted according to the first and second substrates, and the first and second electronic parts.

16. A packaging method for electronic parts according to claim 1, wherein the first substrate
25 includes a sustaining member provided within the opening and sustaining an exposed surface of the resin.

17. A packaging method for electronic parts

according to claim 16, wherein a fin for cooling is bonded to the second electronic part.

18. A packaging method for electronic parts according to claim 1, wherein the second substrate has
5 a stiffener for reinforcement.

19. A packaging method for electronic parts according to claim 18, wherein the stiffener is provided on the side of the first electronic part.

20. A packaging method for electronic parts
10 according to claim 18, wherein the stiffener is provided on an outer peripheral edge of the thin film substrate.